

ABSTRACT OF THE DISCLOSURE

The object of the present invention is to provide an epoxy resin composition which is excellent in flash characteristics and thermal conductivity, and gives an area mounting type semiconductor apparatus having little warpage and excellent temperature cycle properties. According to the present invention, there is provided an epoxy resin composition for semiconductor encapsulation which comprises, as essential components, (A) a spherical alumina, (B) an ultrafine silica having a specific surface area of 120-280 m²/g, (C) a silicone compound, (D) an epoxy resin, (E) a phenolic resin as a curing agent, and (F) a curing accelerator, in which said ultrafine silica is contained in an amount of 0.2-0.8% by weight based on the total weight of the resin composition, and said silicone compound is a polyorganosiloxane and is contained in an amount of 0.3-2.0% by weight based on the total weight of the resin composition.